

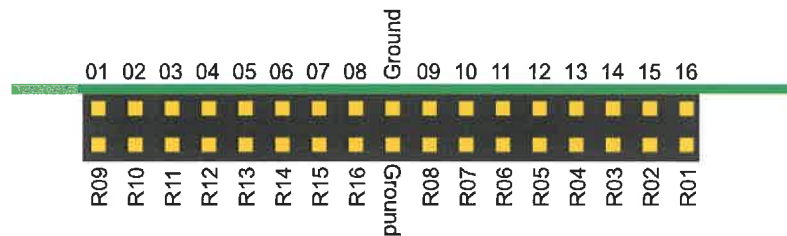
Drg. No **A-4246**

Detail of thick thin metal

Rear

Front

Connector Lifted Approx 1.5mm up from the surface of the ceramic for ease of soldering.



Drawn N.W	Checked S.W	Date 28/01/2014	Tolerances Unless Stated	Outputs Via: Samtec PI No. TSW-117-09-G-D-RA
Des. Appd.			x.x = ± 0.1 mm	Mating connector: R,S Part number 674-1117
Micron			x.xx = ± 0.01 mm	Potted Wire Bonds: No
			Angular ± 0.25°	Substrate Number: A-2540
			Material Thickness ± 0.05 mm	Substrate Material: 1.6 mm thick Ceramic
				Connector Orientation: Exiting Rear Side

Title.  
**Design W D/S Type 9TT/2M  
Ceramic Package  
3D Assembly.**

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Scale N/A      Dims in. mm      Drg No **A-4246**